ProbePads 05

CPWG to microstrip transition

APPLICATIONS
- Device characterization
- Microwave integrated circuits
- On-wafer microwave measurements
- De-embedding

FEATURES
- Wire bondable Au contacts
- Eutectic, epoxy, or solder die attach
- Compact and low profile
- 99.6% Alumina
- Thin-film process

SPECIFICATIONS

TABLE 1: TYPICAL SPECIFICATIONS*

<table>
<thead>
<tr>
<th>FREQ (GHz)</th>
<th>PART NUMBER</th>
<th>INSERTION LOSS (dB)</th>
<th>RETURN LOSS (dB)</th>
<th>SUBSTRATE</th>
<th>PROBE TIP SPACING</th>
<th>SIZE (MILS)</th>
</tr>
</thead>
<tbody>
<tr>
<td>DC-26.5</td>
<td>PPS-005-01</td>
<td>0.25</td>
<td>20</td>
<td>99.6% ALUMINA</td>
<td>150-250 um</td>
<td>65 X 38 X 5</td>
</tr>
</tbody>
</table>

* Specifications subject to change without notice.

MECHANICAL

* Dimensions are mils
- 99.6% Alumina
- Metallization: Gold
TYPICAL PERFORMANCE

Data taken with two back-to-back ProbePads 05 mounted on a gold-plated copper tungsten carrier with Epo-Tek H20E epoxy. Measured on a probe station with GGB EPC40-GSG-150 probes and CS5 calibration substrate.
ORDERING INFO

**Product Code:**

- **PPS**
- **005**
- **01**

**Packaging:** Waffle Pack

The PPS-005-01 is a lead free, RoHS compliant product.